

**HDBNC SERIES**

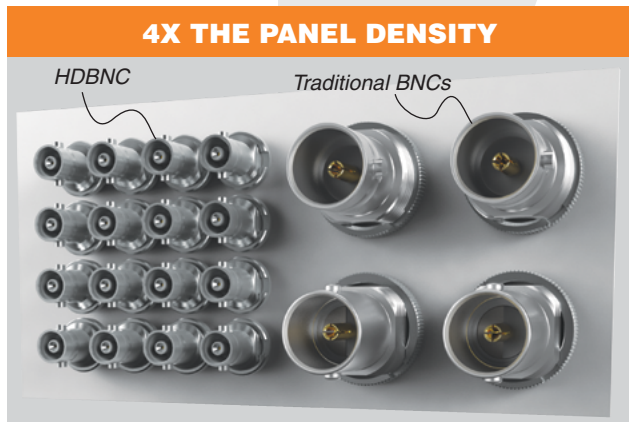
# 75 Ω HIGH-DENSITY BNC JACKS

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see [www.samtec.com?HDBNC-TH](http://www.samtec.com?HDBNC-TH), [www.samtec.com?HDBNC-BH1](http://www.samtec.com?HDBNC-BH1) or [www.samtec.com?HDBNC-EM](http://www.samtec.com?HDBNC-EM)

- Shell Material:**  
Au plated Brass
- Contact Material:**  
Copper Alloy
- Insulator Material:**  
PTFE
- Impedance:**  
75 Ω ±2 Ω
- Voltage Rating:**  
500 VAC
- Dielectric Withstanding:**  
1500 Vrms min
- Operating Temperature:**  
-65 °C to +125 °C
- RoHS Compliant:**  
Yes
- Lead-Free Solderable:**  
Yes

**Mates with:**  
RFB6T, RFB8T, RFA6T



Patented design and bayonet latch

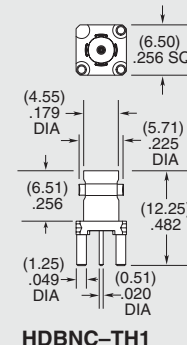
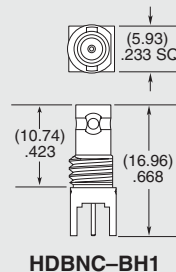
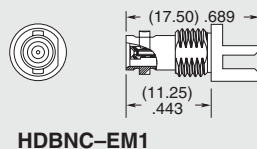
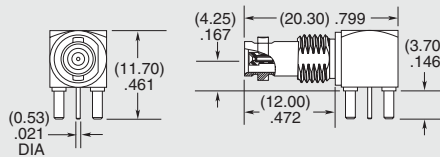
20% reduction in weight of traditional BNCs

Extended performance of 12G for high density terminations

**EXTRACTION TOOL**

- Hand tool for quickly installing/uninstalling HDBNC Series.  
Part Number: CAT-EX-HDBNC-01  
Contact Samtec.

HDBNC	GENDER	TYPE	PLATING	ORIENTATION	TERMINATION
-J	= Jack	-P = PCB Mount	-GN = 10 μ" (0.25 μm) Gold contact, 100 μ" (2.54 μm) Nickel shell	-ST = Straight  -RA = Right-angle	-BH1 = Through-hole  -BH2 = Through-hole (2.36 mm) .093 Board (-RA only)  -EM1 = Edge Mount (-ST only)  -TH1 = Through-hole (-ST only)



**Notes:**  
Compatible with Amphenol's HD-BNC™

Designed to meet SMPTE 424M 12G-SDI specifications.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.